

RB521S-30

Schottky Barrier Diode





Features

- V_R 30V
- I_F 200mA

Typical Applications

Low Forward Voltage Drop

Mechanical Data

- Package: SOD-523
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Cathode line denotes the cathode end
- Marking: C

■Limiting Values (Absolute Maximum Rating)

| Item | Symbol | Unit | Conditions | Limit Max |
|---|------------------|------|-----------------------------|--------------|
| Power Dissipation | P _D | mW | | 150 |
| Storage Temperature | T _{STG} | °C | | -40 to +125 |
| Junction Temperature | TJ | °C | | -40 to +125 |
| DC Reverse Voltage | V_R | V | | 30 |
| Average Rectified Forward Current | I _{FAV} | mA | | 200 |
| Non-repetitive Peak Forward Surge Current | I _{FSM} | Α | 8.3ms single half sine-wave | 1.0 |

■Electrical Characteristics (Ta=25°C Unless otherwise specified)

| Item | Symbol | Unit | Conditions | Min | Тур | Max |
|-------------------------|----------------|------|------------------------------|-----|------|------|
| Breakdown Voltage | V _R | V | I _R = 500uA | 30 | | |
| Converd Voltage | V _F | ٧ | I _F =10mA | | | 0.35 |
| Forward Voltage | | | I _F =200mA | | 0.43 | 0.5 |
| Reverse Leakage Current | I _R | uA | V _R =10V | | | 30 |
| Junction Capacitance | C _J | pF | F=1.0MHz, V _R =1V | | 10 | 20 |

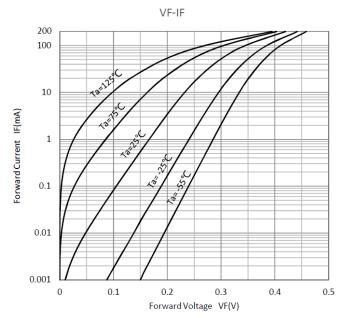
■Ordering Information (Example)

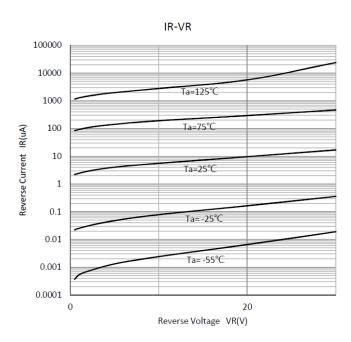
| PREFERED P/N | PACKING CODE | UNIT WEIGHT(g) | MINIMUM PACKAGE(pcs) | INNER BOX QUANTITY(pcs) | OUTER CARTON QUANTITY(pcs) | DELIVERY MODE |
|--------------|-----------------|--------------------|-------------------------|-------------------------|----------------------------|---------------|
| RB521S-30 | F2 | Approximate 0.0025 | 8000 | 80000 | 320000 | 7" reel |

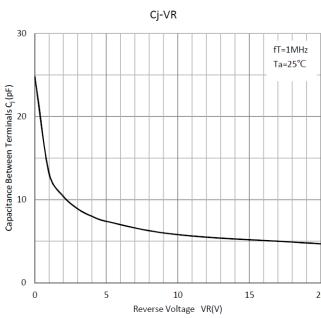


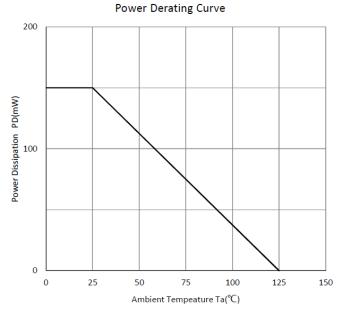


■Characteristics(Typical)



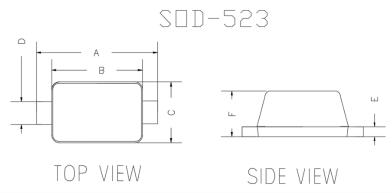






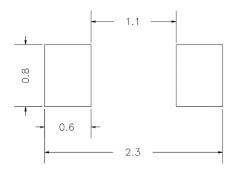


■ SOD-523 Package Outline Dimensions



| DIMENSIONS | | | | | |
|------------|-------|-------|-------|-------|--|
| DIM | INC | HES | ММ | | |
| | MIN | MAX | MN | MAX | |
| Α | 0.059 | 0.067 | 1.500 | 1.700 | |
| В | 0.043 | 0.051 | 1.100 | 1.300 | |
| С | 0.028 | 0.035 | 0.700 | 0.900 | |
| D | 0.010 | 0.014 | 0.250 | 0.350 | |
| E | 0.002 | 0.008 | 0.050 | 0.200 | |
| F | 0.020 | 0.028 | 0.500 | 0.700 | |

■ SOD-523 Soldering Footprint



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT



RB521S-30

Disclaimer

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